Our team develops the systems with modern development tools:

- Concept Development
- 3D Design Environment
- Prototype Systems
- Finite Element Analysis
- Vision System Integration

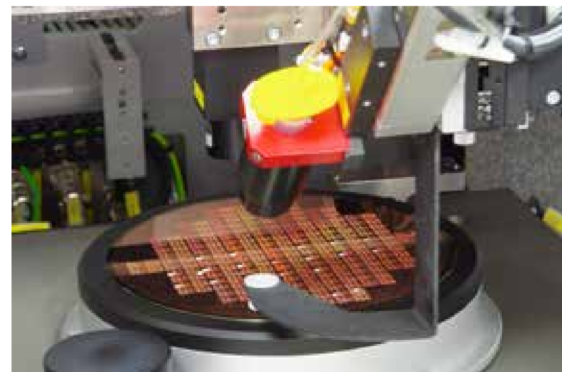
- Software development
- Customized machine controls
- Process vision systems
- Image processing systems

- Process development & process production transfer
- Sampling and small volume production

We are open to custom designs & complete solution developments

For Example:

- Gel Fill Assembly Line
- Pressure Sensor Lid Attach Line
- Customized 6-axis Freedom System
- Integration of unique dispensing systems
- Active alignment system
- Plasma cleaner integration
- FOUP Wafer Loader
- Innovative Submount Fixture Solutions
- Unique Process Gas Solutions
- Wafer Bonding Integration



ASM AMICRA

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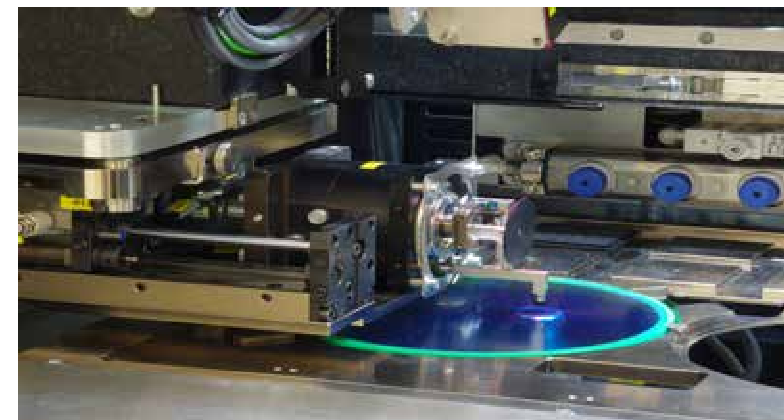
ASM AMICRA follows a policy of continuous product improvement
Products and specifications are subject to change without notice
Version June 2018

ASM AMICRA

ENABLING THE DIGITAL WORLD



Products

Product Solutions,
Advanced Technology,
& Unique Capabilities

Advanced Packaging Die Bonder & Flip Chip Bonders

NANO

ULTRA-PRECISION
DIE & FLIP CHIP BONDER

- Supports ±0.3µm @ 3s placement accuracy
- Supports all die attach and flip chip applications including all AFC^Plus capabilities
- Higher resolution alignment optics
- Active vibration damping system
- Automatic placement offset tuning system
- High resolution 300mm bonding station
- Dynamic alignment system
- Quantitative parallelism calibration

MARKETS

- Single Mode/SiPhotonics/PIC AOC/WLP
- Optical Device Packaging
- Direct Bond Interconnect

AFC^PLUS

FULLY AUTOMATIC SUB-MICRON
DIE & FLIP CHIP BONDER

- Accuracy down to ±1µm @ 3s with cycle-times down to 25 sec AuSn eutectic process
- Eutectic laser soldering or epoxy bonding
- Small die size down to 100µm
- Closed loop bond force control
- Supports all dispensing technologies
- Optional: flip chip bonding, wafer mapping, post bond inspection, heated tools, etc.

MARKETS

- AOC/VCSEL/Multi Mode/Lidar
- Laser Bar and MEMS assembly
- Semiconductor advanced packaging (3D, Stack Die etc.)

NOVA^PLUS

HIGH-SPEED DUAL HEAD
DIE & FLIP CHIP BONDER

- Accuracy down to ±2.5 µm @ 3s with cycle-times down to <3 sec AuSn eutectic process
- Modular machine concept for all micro assembly applications
- Eutectic laser soldering for high-speed assembly
- Supports all dispensing technologies
- Offering automatic tool changers
- Optional: flip chip bonding, wafer mapping, post bond inspection, heated tools, etc.

MARKETS

- AOC/Optoelectronic/Photonics/LED
- Lidar/Laser Bar and MEMS Assembly
- Semiconductor advanced packaging (TSV, eWLB, FanOut, WLP, 3D, Stack Die)

High-Speed Dispense System

HDS

FULLY AUTOMATIC HIGH-SPEED
AND PRECISION DISPENSE SYSTEM

- Quad or dual headed dispensing system
- Underfill, Glob Top, Flux, eneral Dispensing Applications
- Supports all standard dispensing pump technologies (Jet Pump, Spindle Pump, time pressure vacuum pump)
- Cognex Vision System (automatic fiducial mapping, post inspection system)
- Support PCB, laminate strip, leadframes, carriers, etc.
- Inline, magazine to magazine, reel to reel

MARKETS

- MEMS, Automotive, Semiconductor Industry, Electronics

Wafer Inking Systems

AIS & SIS

FULLY AUTOMATIC OR SEMI AUTOMATIC
HIGH-SPEED INKING SYSTEM

- Dot size down to 70 µm
- Inking of diced und undiced wafers down to 20 dots/s
- Automatic wafer loader for up to 12“ wafer